

Part Number: XAUG20C

 $20.32 \mathrm{mm} \; (0.8") \; 16 \; \mathrm{SEGMENT} \; \mathrm{SINGLE} \; \mathrm{DIGIT}$ $\mathrm{ALPHANUMERIC} \; \mathrm{DISPLAY}$

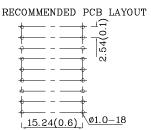


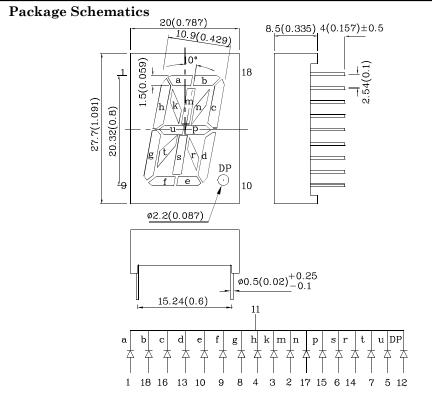
Features

- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant









Notes:

- 1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.
- 2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		UG (GaP)	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	25	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA	
Power Dissipation	P_D	62.5	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)		UG (GaP)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_{R}	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λΡ	565*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	568*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	30	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

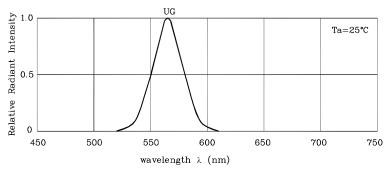
Part Number	Emitting Color	0		ensity Wavelength 07* CIE127-2007* acd nm λP	Description	
			min. t	typ.		
XAUG20C	Green	GaP		0990 390* 565*	Common Cathode, Rt. Hand Decimal.	

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Mar 01.2014

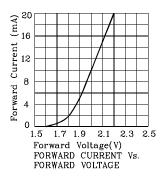
XDSA1138 V7-X Layout: Maggie L.

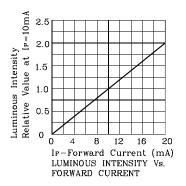


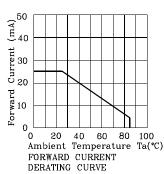


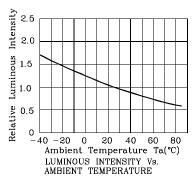
RELATIVE INTENSITY Vs. CIE WAVELENGTH

♦ UG

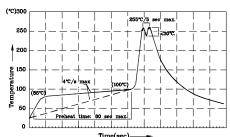








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- nmend pre-heat temperature of 105°C or less (as measured with a noccouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 250°C wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec
- 2.Peak wave soldering temperature betweenax).
 3.Do not apply stress to the epoxy resin (-Pixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

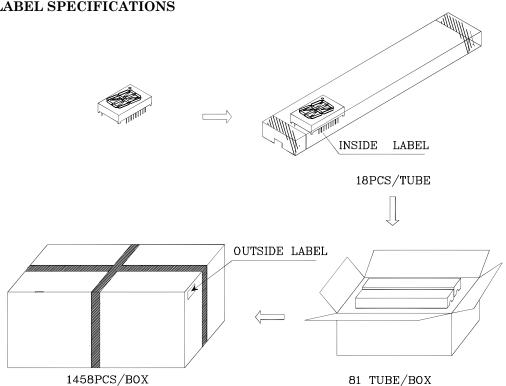


Part Number: XAUG20C

20.32mm (0.8") 16 SEGMENT SINGLE DIGIT ALPHANUMERIC DISPLAY



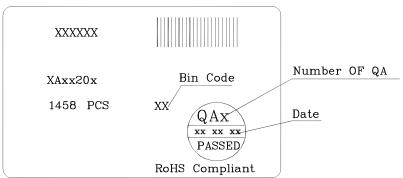
PACKING & LABEL SPECIFICATIONS



Inside Label On IC-tube



Outside Label On Box



TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp